



Micron Leverages 34-Nanometer NAND Process to Produce Highest Density Multi-Chip Package for High-End Mobile Phones

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Boise, Idaho , Thursday, February 12, 2009 – Micron Technology, Inc., today announced that it is currently sampling the industry's highest density all-in-one NAND-based multi-chip package (MCP), a solution including 16GB of multi-level cell (MLC) NAND, for high-end mobile phones. The MCP leverages Micron's industry-leading 32 gigabit (Gb) 34-nanometer (nm) MLC NAND technology, enabling the company to achieve such high density in a single package.

The mobile industry is experiencing a convergence across the newly charted middle ground between ultra-mobile PCs and highly functional, full-featured smart phones. This blurring of the lines between these applications is driving handset manufacturers to increase storage capacity and computing power to enable integration of additional features and applications— while having to maintain a slim form factor. To do this, handset manufacturers are looking for cutting edge memory-stacking solutions that allow for the design of high-density storage directly on-board, in a single package.

Micron's new all-in-one MCP stacks eight die to deliver an unprecedented 16GBs of available on-board storage, therefore eliminating the need for an external memory card slot. And with the space savings that the device offers—which, in some designs, could mean board-space savings of up to 40%—handset manufacturers can capitalize on greater density, yet continue to deliver sleek handset designs. Specific components of the 16GB all-in-one solution include:

- **e-MMC memory, featuring one controller with four 32Gb, 34nm MLC NAND die.** Micron's e-MMC is a managed NAND solution that combines NAND flash with a high-speed MultiMediaCard (MMC) controller that improves overall system performance by easing device integration, providing greater error correction, and removing some of the NAND management burden placed on the host processor.
- **Low-power DDR memory.** 2GBs of Micron's Low-power DDR provides the necessary memory for quick access to frequently used data in the handset. And with its low power of 1.8 volts and other power-saving features, battery life is extended.
- **2Gb single-level cell (SLC) NAND.** Designed to offer high reliability, Micron SLC NAND is an ideal solution for storage and execution of critical code and applications.

With this combination of the handset's memory and MMC controllers in a single package, Micron is enabling manufacturers to deliver optimum storage and performance. Ultimately, by aggressively applying its manufacturing and stacking prowess, Micron's offering helps mobile designers lower cost; simplify their design process; and speed time to market with greater product connectivity, a simplified vendor list, and lower bill of materials.

"We are encouraged by the shift happening within the mobile industry, bringing with it new opportunities for memory innovations," said Eric Spanneut, director of mobile memory marketing for Micron. "Micron has taken great strides in expanding our mobile memory portfolio and we believe we are in a unique position with our 16GB-based all-in-one solution, empowering our customers to develop original handset designs."

Availability

Micron is currently sampling its 16GB-based MCP solution with select mobile handset designers and will be production ready in the first quarter of 2009. Micron is also sampling 4GB and 8GB densities of the all-in-one MCP solution, which are currently qualified for commercial production.

About Micron

Micron Technology, Inc. is one of the world's leading providers of advanced semiconductor solutions. Through its worldwide operations, Micron manufactures and markets DRAMs, NAND flash memory, CMOS image sensors, other semiconductor components, and memory modules for use in leading-edge computing, consumer, networking, and mobile products. Micron's common stock is traded on the New York Stock Exchange (NYSE) under the MU symbol. To learn more about Micron Technology, Inc., visit www.micron.com.

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This press release contains forward-looking statements regarding the production of Micron's 16GB MCP solution. Actual events or results may differ materially from those contained in the forward-looking statements. Please refer to the documents the Company files on a consolidated basis from time to time with the Securities and Exchange Commission, specifically the Company's most recent Form 10-K and Form 10-Q. These documents contain and identify important factors that could cause the actual results for the Company on a consolidated basis to differ materially from those contained in our forward-looking statements (see Certain Factors). Although we believe that the expectations reflected in the forward-looking statements are reasonable, we cannot guarantee future results, levels of activity, performance or achievements. We are under no duty to update any of the forward-looking statements after the date of this press release to conform to actual results.

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